

View Online at <https://aerobasegroup.com/nsn/8040-01-121-3868>

Physical Form:

Paste

Specific Usage Design:

For bonding semiconductors and other electronic components to chassis or heat sinks

Features Provided:

Separate catalyst

Special Features:

Thermally conductive

Color:

Natural

Material:

Plastic epoxy

Shelf Life:

N/a

Unit Of Measure:

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Demilitarization:

No

Fiig:

A535p0